

Technical Data Sheet

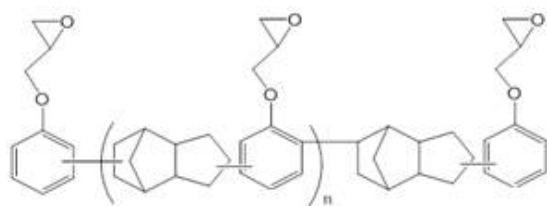
KES-7680M75

DCPD-Phenol Epoxy

General Description

The DCPD-Phenol epoxy resin KES-7680M75 is a epoxy resin derived from poly-addition compound of dicyclopentadiene and Phenol. KES-7680M75 is a soluted product by 25wt% methyl ethyl ketone. KES-7680M75 is designed for application of high performance epoxy molding compound for semi-conductor and copper clad laminates for PCB because of its excellent electrical properties. Especially this product has low Dk (dielectric constant) and Df (low dielectric loss) properties, so it can be used for high speed PCB.

Chemical Structure



Resin Properties

Property	Typical values
EEW (g/eq)	255 ~ 290
S.P. (°C)*	75 ~ 85
Hy-Cl (ppm)	500 Max
N.V.(wt.%)*	75±1

* Mettler 2°C/min

Usage

1. CCL laminate for high speed PCB
2. Carbon fiber prepreg laminate
3. Electronic encapsulation and transfer molding
4. Electrical heat resistance molding compound
5. Lead free type CCL laminate varnish additives
6. High temperature adhesives and structural composites
7. Tooling, casting & molding compounds

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handing procedures are discussed in the information on the MSDS should reviewed and understood before working.

Packaging

Can of 20kg net weight

Drum of 200kg net weight